

# LMC604x CMOS, Dual, Micropower Operational Amplifiers

#### 1 Features

- Typical values unless otherwise noted
- Low supply current: 10µA/amp
- Supply range: 4.5V to 15V, single supply
- Ultra-low input current: 2fA
- Rail-to-rail output swing
- Input common-mode includes ground

# 2 Applications

- Battery monitoring and power conditioning
- Photodiode and infrared-detector preamplifier
- Silicon-based transducer systems
- Portable analytic instruments
- pH-probe buffer amplifier
- Fire- and smoke-detection systems
- Charge amplifier for piezoelectric transducers

## 3 Description

Ultra-low power consumption and low input-leakage current are the hallmarks of the LMC6041, LMC6042, and LMC6044 (LMC604x). Providing input currents of only 2fA (typical), the LMC604x operate from a single supply, with an output swing extending to each supply rail and an input voltage range that includes ground.

The LMC604x are designed for use in systems requiring ultra-low power consumption. In addition, the insensitivity to latch-up, the high output drive, and an output swing to ground without requiring external pulldown resistors make these op amps an excellent choice for single-supply, battery-powered systems.

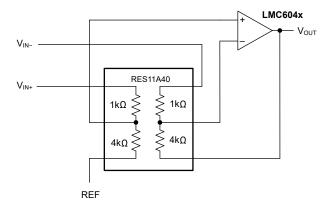
applications for the LMC604x include barcode-reader amplifiers, magnetic- and electric-field detectors, and portable electrometers.

This device is built with TI's advanced double-poly silicon-gate CMOS process.

#### **Device Information**

PART NUMBER	CHANNEL COUNT	PACKAGE <sup>(1)</sup>
LMC6041	Single	D (SOIC, 8)
LIVICOU4 I	Single	P (PDIP, 8)
LMC6042	Dual	D (SOIC, 8)
LIVIC0042	Duai	P (PDIP, 8)
LMC6044	Quad	D (SOIC, 14)
LMC6044	Quad	N (PDIP, 14)

For more information, see Section 9.



**Difference Amplifier Application With RES11A** 



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# **4 Pin Configuration and Functions**

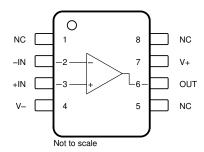


Figure 4-1. LMC6041: D Package, 8-Pin SOIC, and P Package, 8-Pin PDIP (Top View)

Table 4-1. Pin Functions: LMC6041

PIN		TYPE	DESCRIPTION			
NAME	NO.	ITPE	DESCRIPTION			
-IN	2	Input	Inverting input			
+IN	3	Input	Noninverting input			
NC	1, 5, 8	_	No connection. Leave unconnected or float this pin.			
OUT	6	Output	Output			
V-	4	Power	Negative (lowest) power supply			
V+	7	Power	Positive (highest) power supply			

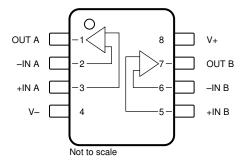


Figure 4-2. LMC6042: D Package, 8-Pin SOIC, and P Package, 8-Pin PDIP (Top View)

Table 4-2. Pin Functions: LMC6042

	PIN			
NAME	NO.	TYPE	DESCRIPTION	
–IN A	2	Input	Inverting input channel A	
–IN B	6	Input	Inverting input channel B	
+IN A	3	Input	Noninverting input channel A	
+IN B	5	Input	Noninverting input channel B	
OUT A	1	Output	Output channel A	
OUT B	7	Output	Output channel B	
V-	4	Power	Negative supply	
V+	8	Power	Positive supply	



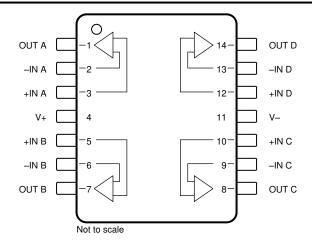


Figure 4-3. LMC6044: D Package, 14-Pin SOIC, and N Package, 14-Pin PDIP (Top View)

Table 4-3. Pin Functions: LMC6044

	PIN	TVDE	DESCRIPTION
NAME	NO.	TYPE	DESCRIPTION
–IN A	2	Input	Inverting input channel A
–IN B	6	Input	Inverting input channel B
–IN C	9	Input	Inverting input channel C
–IN D	13	Input	Inverting input channel D
+IN A	3	Input	Noninverting input channel A
+IN B	5	Input	Noninverting input channel B
+IN C	10	Input	Noninverting input channel C
+IN D	12	Input	Noninverting input channel D
OUT A	1	Output	Output channel A
OUT B	7	Output	Output channel B
OUT C	8	Output	Output channel C
OUT D	14	Output	Output channel D
V-	11	Power	Negative supply
V+	4	Power	Positive supply

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# 5 Specifications

# 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1) (2)

			MIN MAX	UNIT
	Differential input voltage		±Supply voltage	;
Vs	Supply voltage, $V_S = (V+) - (V-)$		10	S V
	Output short circuit <sup>(5)</sup>	To V+	See <sup>(3</sup>	)
I <sub>SC</sub>	Output short circuit.	To V-	See <sup>(4</sup>	
	Voltage at input/output pin		(V-) - 0.3 (V+) + 0.3	B V
	Current at input pin		±:	5
	Current at output pin		±18	mA
	Current at power supply pin		3:	5
P <sub>D</sub>	Power dissipation		See(5	)
	Lead temperature (soldering, 10s)		260	°C
TJ	Junction temperature <sup>(5)</sup>		110	°C
T <sub>stg</sub>	Storage temperature		<b>–</b> 65 150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (3) Do not connect output to V+ when V+ is greater than 13V or reliability can be adversely affected.
- (4) Applies to both single-supply operation. Continuous short-circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 110°C. Output currents in excess of ±30mA over the long term can adversely affect reliability.
- (5) The maximum power dissipation is a function of  $T_{J(Max)}$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(Max)} T_A) / \theta_{JA}$ .

#### 5.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±500	V

<sup>(1)</sup> JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.

#### 5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM M	٩X	UNIT
	$V_S$ Supply voltage, $V_S = (V+) - (V-)$	Single supply	4.5	1	5.5	.,
Vs	Supply voltage, $v_S = (v+) = (v-)$	Dual supply	±2.25	±7	75	V
P <sub>D</sub>	Power dissipation			Sec	(1)	
	Specified temperature		-40	4	85	°C

(1) To operate the device at elevated temperatures, derate the device based on thermal resistance  $\theta_{JA}$  with  $P_D = (T_J - T_A) / \theta_{JA}$ .



## 5.4 Thermal Information: LMC6041

		LMC	C6041	
	THERMAL METRIC <sup>(1)</sup>	D (SOIC)	P (PDIP)	UNIT
		8 PINS	8 PINS	
R <sub>0JA</sub>	Junction-to-ambient thermal resistance	165.0	101.0	°C/W
R <sub>0JC(top)</sub>	Junction-to-case(top) thermal resistance	57.9	52.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	62.3	38.4	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	10.0	18.5	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	61.5	37.4	°C/W
R <sub>0JC(bot)</sub>	Junction-to-case(bottom) thermal resistance	N/A	N/A	°C/W

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

### 5.5 Thermal Information: LMC6042

		LMC	C6042	
	THERMAL METRIC <sup>(1)</sup>	D (SOIC)	P (PDIP)	UNIT
		8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	165.0	101.0	°C/W
R <sub>0JC(top)</sub>	Junction-to-case(top) thermal resistance	52.0	52.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	56.9	38.4	°C/W
ΨЈТ	Junction-to-top characterization parameter	6.8	18.5	°C/W
ΨЈВ	Junction-to-board characterization parameter	56.1	37.4	°C/W
R <sub>0JC(bot)</sub>	Junction-to-case(bottom) thermal resistance	N/A	N/A	°C/W

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

# 5.6 Thermal Information: LMC6044

		LMC	LMC6044		
	THERMAL METRIC <sup>(1)</sup>	D (SOIC)	N (PDIP)	UNIT	
		14 PINS	14 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	115.0	85.0	°C/W	
R <sub>0JC(top)</sub>	Junction-to-case(top) thermal resistance	34.6	28.1	°C/W	
R <sub>0JB</sub>	Junction-to-board thermal resistance	34.3	32.8	°C/W	
ΨЈТ	Junction-to-top characterization parameter	4.7	15.9	°C/W	
ΨЈВ	Junction-to-board characterization parameter	33.7	32.3	°C/W	
R <sub>0JC(bot)</sub>	Junction-to-case(bottom) thermal resistance	N/A	N/A	°C/W	

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



# **5.7 Electrical Characteristics**

	PARAMETER	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
OFFSET	VOLTAGE						
					±1	±3	
		LMC604xAI	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$			±3.3	
Vos	Input offset voltage				±1	±6	mV
		LMC604xI	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$			±6.3	
dV <sub>OS</sub> /dT	Input offset voltage drift	T <sub>A</sub> = -40°C to +85°C			1.3		μV/°C
			LMC604xAI	68	75		
		Positive	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	66			
		5V ≤ V+ ≤ 15V, V <sub>OUT</sub> = 2.5V	LMC604xI	62	75		
2022	Power-supply rejection		LMC604xI, T <sub>A</sub> = -40°C to +85°C	60			4D
PSRR	ratio		LMC604xAI	84	94	±4	dB
		Negative	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	83			
		$0V \le V - \le -10V$ , $V_{OUT} = 2.5V$	LMC604xI	74	94		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	73			
INPUT B	IAS CURRENT	•			-		
	Innut bing assessed				±2		fA
I <sub>B</sub>	Input bias current	$T_A = -40$ °C to +85°C				±4	pA
	Innut offset surrent				±1		fA
los	Input offset current	$T_A = -40$ °C to +85°C			-	±2	pA
NOISE				·			
e <sub>n</sub>	Input voltage noise density	f = 1kHz			83		nV/√Hz
i <sub>n</sub>	Input current noise density	f = 1kHz			12.5		fA/√Hz
THD	Total harmonic distortion	f = 1kHz, gain = - 5V/V, R <sub>L</sub> = 100k	$\Omega$ , $V_{OUT} = 12V_{pp}$ , $V = 15V$		1		%
INPUT V	OLTAGE						
				(V+) - 2.3	(V+) - 1.9		
		To positive rail V+ = 5V and 15V, CMRR ≥ 50dB	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	(V+) - 2.5			
V <sub>CM</sub>	Common-mode voltage	V OV and 10V, Civil at 2 cods	LMC604xI, T <sub>A</sub> = -40°C to +85°C	(V+) - 2.4			V
		To negative rail			- 0.4	- 0.1	
		V+ = 5V and 15V, CMRR ≥ 50dB	T <sub>A</sub> = -40°C to +85°C			0	
			LMC604xAI	68	75		dB
OMBB	Common-mode rejection	V+ = 15V,	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	66			
CMRR	ratio	0V ≤ V <sub>CM</sub> ≤ 12V	LMC604xI	62	75		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	60			
INPUT IN	MPEDANCE	•	1				
R <sub>IN</sub>	Input resistance				>10		ΤΩ



	PARAMETER	TEST CO	TEST CONDITIONS		TYP	MAX	UNIT
OPEN-L	OOP GAIN						
			LMC604xAI	300	1000		
		Sourcing, V+ = 15V,	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	200			
		$7.5V \le V_0 \le 11.5V$ , R <sub>L</sub> = 100kΩ to V+ / 2	LMC604xI	300	1000		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	200			
			LMC604xAI	180	500		
		Sinking, V+ = 15V,	LMC604xAI, $T_A = -40$ °C to +85°C	120			
		$2.5V \le V_0 \le 7.5V$ , R <sub>1</sub> = 100kΩ to V+ / 2	LMC604xI	90	500		
	0		LMC604xI, T <sub>A</sub> = -40°C to +85°C	70			\
A <sub>OL</sub>	Open-loop voltage gain		LMC604xAI	200	1000	v	V/mV
		Sourcing, V+ = 15V, 7.5V $\leq$ V <sub>O</sub> $\leq$ 11.5V, R <sub>L</sub> = 25k $\Omega$ to V+ / 2	LMC604xAI, $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	160			
			LMC604xI	100	1000		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	80			
			LMC604xAI	100	250		
		Sinking, V+ = 15V, $2.5V \le V_O \le 7.5V$ , $R_L = 25k\Omega$ to V+ / 2	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	60			
			LMC604xI	50	250		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	40			
REQU	ENCY RESPONSE						
SBW	Gain bandwidth product	LMC6041			75		kHz
JD V V	Cain bandwidth product	LMC6042 and LMC6044			100		KI IZ
			LMC604xAI	0.015	0.02		
SR	Slew rate <sup>(1)</sup>	V+ = 15V, 10V step, gain = 1	LMC604xAI, $T_A = -40$ °C to +85°C	0.010			V/µs
J1 (	Glew Tales	v · - 10 v, 10 v step, gail - 1	LMC604xI	0.010	0.02		V/μS
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	0.007			
	Crosstalk	Dual and quad channel, V+ = 15V, $R_L$ = 100k $\Omega$ , f = 100Hz, $V_{OUT}$ = 12V <sub>pp</sub>			115		dB



	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
UTPUT							
			LMC604xAI	4.970	4.987		
		Positive rail	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	4.950			
		$V+ = 5V$ , $R_L = 100k\Omega$ to $V+ / 2$	LMC604xI	4.940	4.987		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	4.910			
			LMC604xAI		0.004	0.030	
		Negative rail	LMC604xAI, T <sub>A</sub> = -40°C to +85°C			0.050	
		$V+ = 5V$ , $R_L = 100k\Omega$ to $V+ / 2$	LMC604xI		0.004	0.060	
			LMC604xI, T <sub>A</sub> = -40°C to +85°C			0.090	
			LMC604xAI	4.920	4.980		
		Positive rail V+ = 5V, R <sub>L</sub> = 25kΩ to V+ / 2	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	4.870			
			LMC604xI	4.870	4.980		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	4.820			
			LMC604xAI		0.010	0.080	
		Negative rail	LMC604xAI, T <sub>A</sub> = -40°C to +85°C			0.130	
		$V = 5V$ , $R_L = 25k\Omega$ to $V + / 2$	LMC604xI		0.010	0.130	
	Voltago output swing		LMC604xI, T <sub>A</sub> = -40°C to +85°C			0.180	V
	Voltage output swing	Positive rail V+ = 15V, $R_L$ = 100k $\Omega$ to V+ / 2	LMC604xAI	14.920	14.970		V
			LMC604xAI, T <sub>A</sub> = -40°C to +85°C	14.880			
			LMC604xI	14.880	14.970		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	14.820			
			LMC604xAI		0.007	0.030	
		Negative rail	LMC604xAI, $T_A = -40$ °C to +85°C			0.050	
		$V+ = 15V$ , $R_L = 100k\Omega$ to $V+ / 2$	LMC604xI		0.007	0.060	
			LMC604xI, T <sub>A</sub> = -40°C to +85°C			0.090	
			LMC604xAI	14.900	14.950		
		Positive rail	LMC604xAI, $T_A = -40$ °C to +85°C	14.850			
		$V+ = 15V$ , $R_L = 25k\Omega$ to $V+ / 2$	LMC604xI	14.850	14.950		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	14.800			
			LMC604xAI		0.022	0.100	
		Negative rail	LMC604xAI, T <sub>A</sub> = -40°C to +85°C			0.150	
		15 45 V D 05 10 V V V0	LMC604xI		0.022	0.150	
			LMC604xI, T <sub>A</sub> = -40°C to +85°C			0.200	



	PARAMETER	TEST (	CONDITIONS	MIN	TYP	MAX	UNIT
			LMC604xAI	16	22		
		Sourcing	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	10			
		$V+ = 5V$ , $V_{OUT} = 0V$	LMC604xI	13	22		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	8			
			LMC604xAI	16	21		
		Sinking	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	8			
		$V+ = 5V$ , $V_{OUT} = 0V$	LMC604xI	13	21		
	Short-circuit current		LMC604xI, T <sub>A</sub> = -40°C to +85°C	8			A
I <sub>SC</sub>	Short-circuit current		LMC604xAI	15	40		mA
		Sourcing	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	10			
		$V + = 15V, V_{OUT} = 0V$	LMC604xI	15	40		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	10			
			LMC604xAI	24	39		
		Sinking	LMC604xAI, T <sub>A</sub> = -40°C to +85°C	8			
		V+ = 15V, V <sub>OUT</sub> = 0V	LMC604xI	21	39		
			LMC604xI, T <sub>A</sub> = -40°C to +85°C	8			



	PARAMETER		TEST CONDITIONS		TYP	MAX	UNIT
OWER SU	JPPLY						
			LMC6041AI		14	20	
			LMC6041AI, T <sub>A</sub> = -40°C to +85°C			24	
			LMC6041I		14	26	
			LMC6041I, T <sub>A</sub> = -40°C to +85°C			30	
			LMC6042AI		20	34	
		., -,	LMC6042AI, T <sub>A</sub> = -40°C to +85°C			39	
		V+ = 5V	LMC6042I		20	45	
			LMC6042I, T <sub>A</sub> = -40°C to +85°C			50	
			LMC6044AI		40	65	
			LMC6044AI, T <sub>A</sub> = -40°C to +85°C			72	
			LMC6044I		40	75	
			LMC6044I, T <sub>A</sub> = -40°C to +85°C			82	
	Quiescent current, total		LMC6041AI		18	26	μ
			LMC6041AI, T <sub>A</sub> = -40°C to +85°C			31	
			LMC6041I		18	34	
			LMC6041I, T <sub>A</sub> = -40°C to +85°C			39	
			LMC6042AI		26	44	
		V+ = 15V	LMC6042AI, T <sub>A</sub> = -40°C to +85°C			51	
		V+ - 15V	LMC6042I		26	56	
			LMC6042I, T <sub>A</sub> = -40°C to +85°C			65	
			LMC6044AI		52	85	
			LMC6044AI, T <sub>A</sub> = -40°C to +85°C			94	
			LMC6044I		52	98	
			LMC6044I, T <sub>A</sub> = -40°C to +85°C			107	

<sup>(1)</sup> Number specified is the slower of the positive and negative slew rates.



### **5.8 Typical Characteristics**

at  $V_S = \pm 7.5V$  and  $T_A = 25^{\circ}C$  (unless otherwise specified)

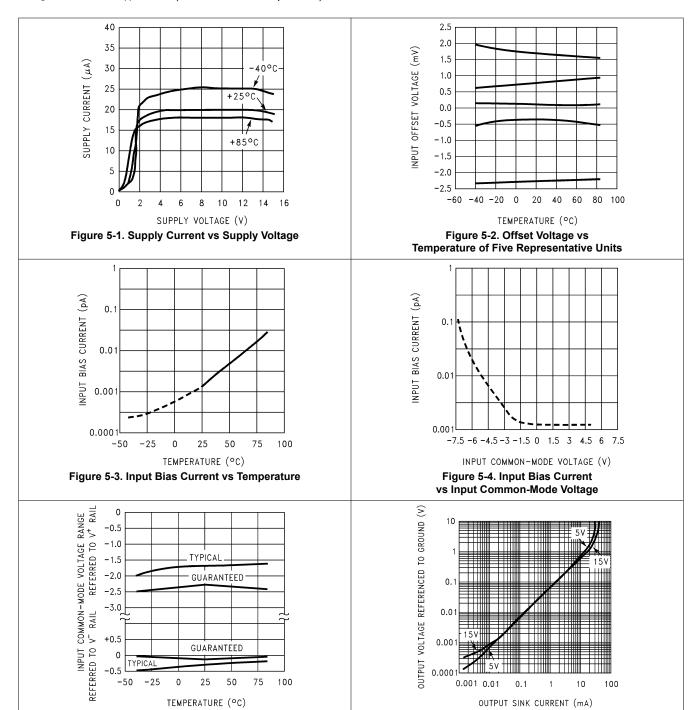
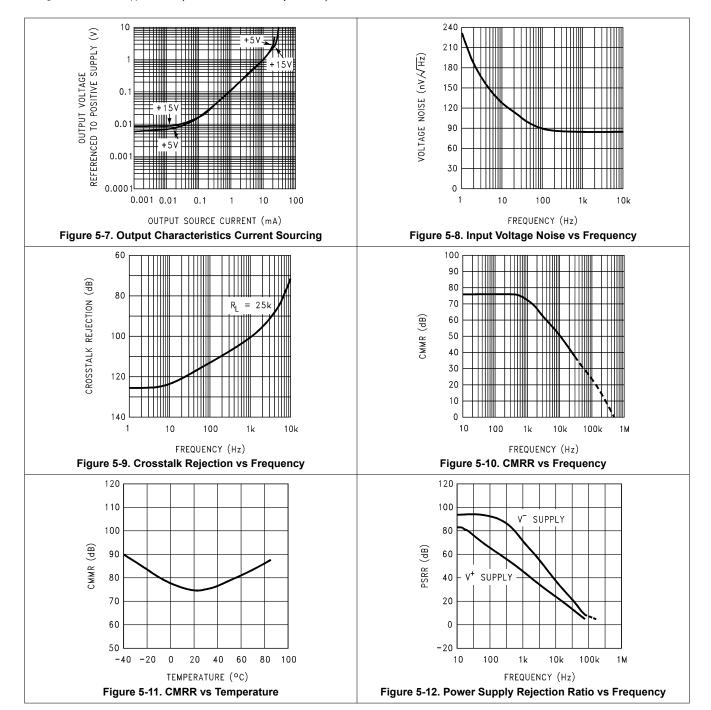


Figure 5-5. Input Bias Current Voltage Range vs Temperature

Figure 5-6. Output Characteristics Current Sinking

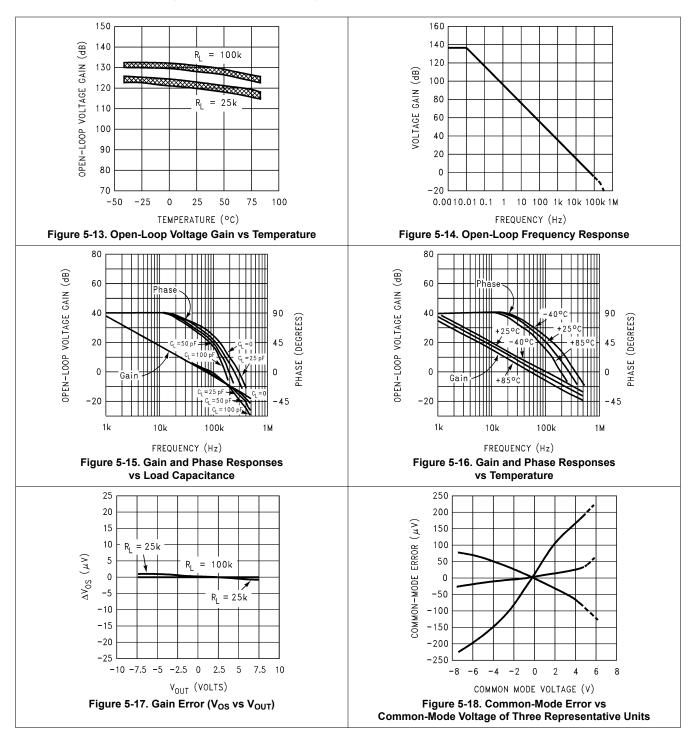


at  $V_S = \pm 7.5V$  and  $T_A = 25^{\circ}C$  (unless otherwise specified)



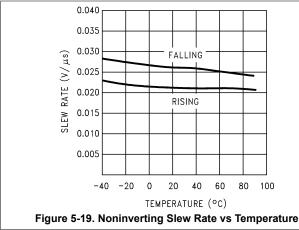


at  $V_S = \pm 7.5V$  and  $T_A = 25^{\circ}C$  (unless otherwise specified)





at  $V_S = \pm 7.5V$  and  $T_A = 25$ °C (unless otherwise specified)



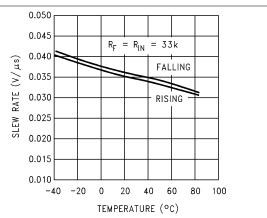


Figure 5-20. Inverting Slew Rate vs Temperature

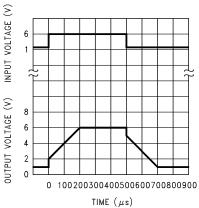


Figure 5-21. Noninverting Large Signal Pulse Response  $(A_V = +1)$ 

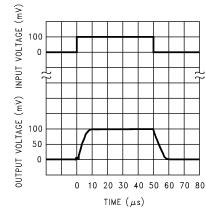


Figure 5-22. Noninverting Small-Signal Pulse Response

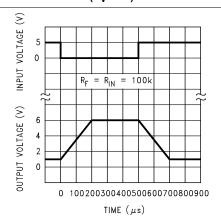


Figure 5-23. Inverting Large-Signal Pulse Response

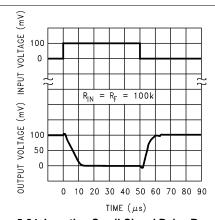
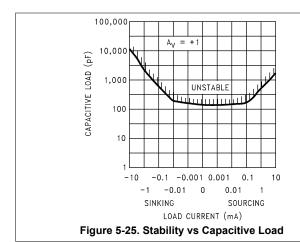
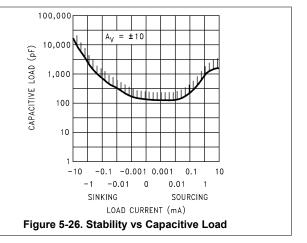


Figure 5-24. Inverting Small-Signal Pulse Response



at  $V_S$  = ±7.5V and  $T_A$  = 25°C (unless otherwise specified)







# 6 Application and Implementation

#### **6.1 Application Information**

#### 6.1.1 Amplifier Topology

The LMC604x incorporate a novel op-amp design topology that enables a rail-to-rail output swing even when driving a large load. Special compensation design techniques are incorporated to maintain stability over a wider range of operating conditions than traditional micropower op amps. These features make the LMC604x both easier to design in, and provide higher speed than products typically found in this ultra-low power class.

#### 6.1.2 Compensating For Input Capacitance

Large values of feedback resistance are quite common for amplifiers with ultra-low input current, such as the LMC604x.

Although the LMC604x are highly stable over a wide range of operating conditions, certain precautions must be taken to achieve the desired pulse response when a large feedback resistor is used. Large feedback resistors and even small values of input capacitance, due to transducers, photodiodes, and circuit board parasitics, reduce phase margins.

When a high input impedance is demanded, guard the inputs of the LMC604x. Guarding input lines can not only reduce leakage, but lower stray input capacitance as well (see Section 6.3.1.1).

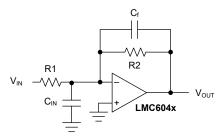


Figure 6-1. Canceling the Effect of Input Capacitance

Compensate for the effect of input capacitance by adding a capacitor. Place a capacitor,  $C_F$ , around the feedback resistor (as in Figure 6-1) so that:

$$\frac{1}{2\pi R1C_{\rm IN}} \ge \frac{1}{2\pi R2C_{\rm F}} \tag{1}$$

where

$$R1C_{IN} \le R2C_F \tag{2}$$

The exact value of  $C_{\text{IN}}$  is often difficult to know, but  $C_{\text{F}}$  can be experimentally adjusted so that the desired pulse response is achieved. See the LMC660 and LMC662 for a more detailed discussion on compensating for input capacitance.



#### 6.1.3 Capacitive-Load Tolerance

Direct capacitive loading reduces the phase margin of many op amps. A pole in the feedback loop is created by the combination of the op-amp output impedance and the capacitive load. This pole induces phase lag at the unity-gain crossover frequency of the amplifier resulting in either an oscillatory or underdamped pulse response. With a few external components, op amps can easily indirectly drive capacitive loads. Figure 6-2 shows an example.

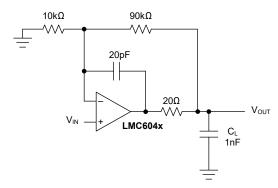


Figure 6-2. LMC604x Noninverting Gain-of-10 Amplifier, Compensated to Handle Capacitive Loads

In the circuit of Figure 6-2, R1 and C1 serve to counteract the loss of phase margin by feeding the high-frequency component of the output signal back into the inverting input of the amplifier, thereby preserving phase margin in the overall feedback loop.

Capacitive load driving capability is enhanced by using a pullup resistor to  $V^+$  (Figure 6-3). Typically, a pullup resistor conducting 10µA or more significantly improves capacitive load responses. The value of the pullup resistor must be determined based on the current sinking capability of the amplifier with respect to the desired output swing. The open-loop gain of the amplifier can also be affected by the pullup resistor (see Section 5.7).

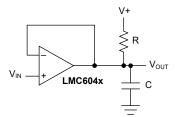


Figure 6-3. Compensating for Large Capacitive Loads With a Pullup Resistor

#### 6.2 Typical Applications

#### 6.2.1 Instrumentation Amplifiers

The extremely high input impedance and low power consumption of the LMC604x make these op amps an excellent choice for applications that require battery-powered instrumentation amplifiers. Examples of these types of applications are portable pH probes, analytic medical instruments, magnetic field detectors, gas detectors, and silicon-based pressure transducers.

The circuit in Figure 6-4 is recommended for applications where the common-mode input range is relatively low and the differential gain is in the range of 10 to 1000. This two op-amp instrumentation amplifier features an independent adjustment of the gain and common-mode rejection trim, and a total quiescent supply current of less than  $20\mu A$ . To maintain ultra-high input impedance, use ground rings and consider printed circuit board (PCB) layout an important part of the overall system design (see Printed Circuit Board Layout for High Impedance Work). Figure 6-4 shows that the input voltages are represented as a common-mode input  $V_{CM}$  plus a differential input  $V_{D}$ .



Rejection of the common-mode component of the input is accomplished by making the ratio of R1/R2 equal to R3/R4. So that:

$$\frac{R3}{R4} = \frac{R2}{R1} \tag{3}$$

The gain equation of the instrumentation amplifier is given by:

$$V_{OUT} = \frac{R4}{R3} \left( 1 + \frac{R3}{R4} + \frac{R2 + R3}{R_0} \right) \tag{4}$$

A suggested design guideline is to minimize the difference of the value between R1 through R4. Minimizing often results in improved resistor temperature coefficient, amplifier gain, and CMRR over temperature. If RN = R1 = R2 = R3 = R4 then the gain equation is simplified as:

$$V_{OUT} = 2V_D \left(1 + \frac{R_N}{R_0}\right) \tag{5}$$

As a result of the *zero-in, zero-out* performance of the LMC604x, and output swing rail-to-rail, the dynamic range is only limited to the input common-mode range of 0V to  $V_S$  – 2.3V, the worst case at room temperature. This feature of the LMC604x makes these op amps an excellent choice for low-power instrumentation systems.

Figure 6-5 shows a complete instrumentation amplifier designed for a gain of 100. Provisions are made for the low-sensitivity trimming of CMRR and gain.

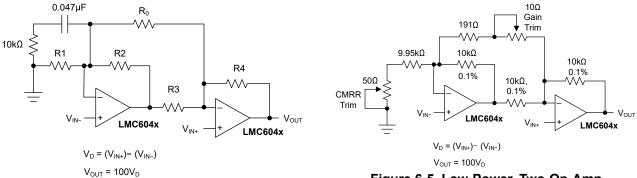


Figure 6-4. Two-Op-Amp Instrumentation Amplifier

Figure 6-5. Low-Power, Two-Op-Amp Instrumentation Amplifier

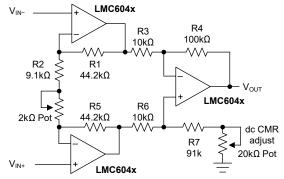


Figure 6-6. Instrumentation Amplifier



#### 6.2.2 Low-Leakage Sample and Hold

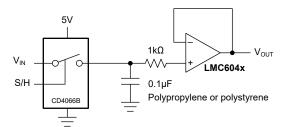


Figure 6-7. Low-Leakage Sample and Hold

## 6.2.3 Square-Wave Generator

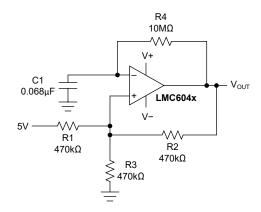


Figure 6-8. 1Hz Square-Wave Oscillator

## 6.2.4 AC Coupled Power Amplifier

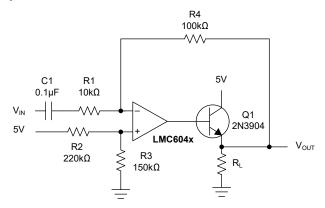


Figure 6-9. AC Coupled Power Amplifier

Submit Document Feedback



### 6.3 Layout

#### 6.3.1 Layout Guidelines

#### 6.3.1.1 Printed-Circuit-Board Layout for High-Impedance Work

As a general rule, any circuit that must operate with less than 1000pA of leakage current requires special layout of the printed circuit board (PCB). To take advantage of the ultra-low input current of the LMC604x, typically 150fA, an excellent layout is essential. Fortunately, the techniques used to obtain low leakages are quite simple. First, do not ignore the surface leakage of the PCB, even though the leakage current can sometimes appear acceptably low, because under conditions of high humidity, dust, or contamination, the surface leakage can be appreciable.

To minimize the effect of any surface leakage, lay out a ring of foil completely surrounding the LMC604x inputs and the terminals of capacitors, diodes, conductors, resistors, relay terminals, and anything else connected to the inputs of the op amp (see also Figure 6-14). To have a significant effect, place guard rings on both the top and bottom of the PCB. Then, connect the foil to a voltage that is at the same voltage as the amplifier inputs, because no leakage current can flow between two points at the same potential. For example, a PCB trace-to-pad resistance of  $10^{12}$ , which is normally considered a very large resistance, can leak 5pA if the trace is a 5V bus adjacent to the pad of the input. This leakage can cause a 250 times degradation from the actual performance of the LMC604x. However, if a guard ring is held within 5mV of the inputs, then even a resistance of  $10^{11}\Omega$  causes only 0.05pA of leakage current. See Figure 6-10 to Figure 6-12 for typical connections of guard rings for standard op-amp configurations

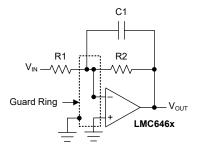


Figure 6-10. Typical Connections of Guard Rings: Inverting Amplifier

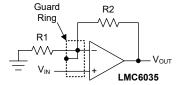


Figure 6-11. Typical Connections of Guard Rings: Noninverting Amplifier

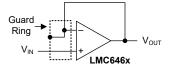
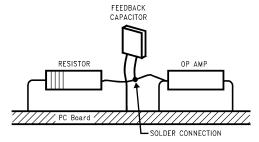


Figure 6-12. Typical Connections of Guard Rings: Follower



If laying out a PCB for the sake of just a few circuits is not practical, the following technique is even better than a guard ring. Do not insert the input pin of the amplifier into the PCB at all. Instead, bend the pin up in the air, and use only air as an insulator because air is an excellent insulator. In this case, you forgo some of the advantages of PCB construction, but the advantages are sometimes well worth the effort of using point-to-point up-in-the-air wiring. Figure 6-13 shows an example of air wiring.



Note: The input pins are lifted out of the PCB and soldered directly to components. All other pins connected to the PCB.

Figure 6-13. Air Wiring

#### 6.3.2 Layout Examples

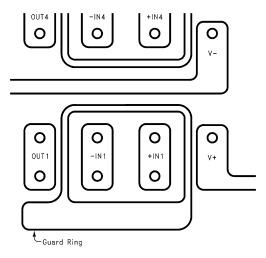


Figure 6-14. Example of Guard Ring in PCB Layout



# 7 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

#### 7.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 7.2 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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## 7.3 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## 7.4 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

# **8 Revision History**

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision E (March 2013) to Revision F (March 2025)	age
• Added LMC6041 and LMC6044 to this data sheet; previously in SNOS610E and SNOS612D, respectively.	1
Added Pin Configuration and Functions	3
Added ESD Ratings	5
Added Thermal Information	6
Updated parameter names and symbols	7
Deleted footnotes 1 and 2 from DC Electrical Characteristics	
Changed input current noise from 0.2fA/√Hz to 12.5fA/√Hz	
Changed total harmonic distortion from 0.01% to 1%	7
Moved footnote 3 from DC <i>Electrical Characteristics</i> to open-loop voltage gain test conditions	
• Changed open-loop gain MIN for $R_L$ = 100k $\Omega$ (sourcing) from 400V/mV to 300V/mV for LMC604xAI	7
• Changed open-loop gain MIN for $R_L$ = 100k $\Omega$ (sourcing, $T_A$ = -40°C to +85°C) from 300V/mV to 200V/mV	
for LMC604xAI	7
Deleted footnotes 1 and 2 from AC Electrical Characteristics	7
Moved footnote 3 test conditions from AC <i>Electrical Characteristics</i> to slew rate test conditions	7
Delete phase margin	
Moved footnote 4 from AC <i>Electrical Characteristics</i> to crosstalk test conditions	7
Updated Amplifier Topology	.17

**LMC6041, LMC6042, LMC6044** SNOS611F – JULY 1999 – REVISED MARCH 2025



CI	hanges from Revision D (March 2013) to Revision E (March 2013)	Page
•	Changed layout of National Data Sheet to TI format	20



# 9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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23-Jun-2025

# **PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
LMC6041AIM/NOPB	Obsolete	Production	SOIC (D)   8	-	-	(4) Call TI	(5) Call TI	-40 to 85	LMC60 41AIM
LMC6041AIMX/NOPB	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes SN Level-1-260C-UNLIM -40 to 85		LMC60 41AIM		
LMC6041AIMX/NOPB.A	Active	Production	SOIC (D)   8	IC (D)   8 2500   LARGE T&R Yes SN Level-1-260C-UNLIM -40 to 85		-40 to 85	LMC60 41AIM		
LMC6041AIMX/NOPB.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 41AIM
LMC6041IM/NOPB	Obsolete	Production	SOIC (D)   8	SOIC (D)   8 Call TI Call TI		-40 to 85	LMC60 41IM		
LMC6041IMX/NOPB	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 41IM
LMC6041IMX/NOPB.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes SN Level-1-260C-UNLIM -40 to 85		-40 to 85	LMC60 41IM	
LMC6041IMX/NOPB.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 41IM
LMC6041IN/NOPB	Obsolete	Production	PDIP (P)   8	-	-	Call TI	Call TI	-40 to 85	LMC60 41IN
LMC6042AIJ	Active	Production	CDIP (NAB)   8	40   TUBE	No	Call TI	Level-1-NA-UNLIM	-	LMC6042AIJ
LMC6042AIJ.A	Active	Production	CDIP (NAB)   8	40   TUBE	No	Call TI	Level-1-NA-UNLIM	See LMC6042AIJ	LMC6042AIJ
LMC6042AIM/NOPB	Obsolete	Production	SOIC (D)   8	-	-	Call TI	Call TI	-40 to 85	LMC60 42AIM
LMC6042AIMX/NOPB	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 42AIM
LMC6042AIMX/NOPB.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 42AIM
LMC6042AIMX/NOPB.B	Active	Production	SOIC (D)   8	SOIC (D)   8 2500   LARGE T&R Yes SN Level-1-260C-UNLIM -40 to 85		-40 to 85	LMC60 42AIM		
LMC6042AIN/NOPB	Obsolete	Production	PDIP (P)   8	-	-	Call TI	Call TI	-40 to 85	LMC60 42AIN
LMC6042IM/NOPB	Obsolete	Production	SOIC (D)   8	-	-	Call TI	Call TI	-40 to 85	LMC60 42IM



-40 to 85

23-Jun-2025

AIM

LMC6044 AIM

LMC6044IM

LMC6044IM

LMC6044IM

LMC6044IN



LMC6044AIMX/NOPB.B

LMC6044IMX/NOPB

LMC6044IMX/NOPB.A

LMC6044IMX/NOPB.B

LMC6044IN/NOPB

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Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
LMC6042IMX/NOPB	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 42IM
LMC6042IMX/NOPB.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 42IM
LMC6042IMX/NOPB.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC60 42IM
LMC6044-MDC	Active	Production	DIESALE (Y)   0	100   TUBE	Yes	Call TI	Level-1-NA-UNLIM	-40 to 85	
LMC6044-MDC.A	Active	Production	DIESALE (Y)   0	100   TUBE	Yes	Call TI	Level-1-NA-UNLIM	-40 to 85	
LMC6044AIM/NOPB	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-40 to 85	LMC6044 AIM
LMC6044AIMX/NOPB	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6044 AIM
LMC6044AIMX/NOPB.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LMC6044

SN

SN

SN

SN

Call TI

Level-1-260C-UNLIM

Level-1-260C-UNLIM

Level-1-260C-UNLIM

Level-1-260C-UNLIM

Call TI

Active

Active

Active

Active

Obsolete

Production

Production

Production

Production

Production

SOIC (D) | 14

SOIC (D) | 14

SOIC (D) | 14

SOIC (D) | 14

PDIP (N) | 14

Yes

Yes

Yes

Yes

2500 | LARGE T&R

2500 | LARGE T&R

2500 | LARGE T&R

2500 | LARGE T&R

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.



# **PACKAGE OPTION ADDENDUM**

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(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMC6041AIMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMC6041IMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMC6042AIMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMC6042IMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMC6044AIMX/NOPB	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1
LMC6044IMX/NOPB	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1



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## \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMC6041AIMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LMC6041IMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LMC6042AIMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LMC6042IMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LMC6044AIMX/NOPB	SOIC	D	14	2500	356.0	356.0	35.0
LMC6044IMX/NOPB	SOIC	D	14	2500	367.0	367.0	35.0

# **PACKAGE MATERIALS INFORMATION**

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## **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
LMC6042AIJ	NAB	CDIP	8	40	502	14	11938	4.32
LMC6042AIJ.A	NAB	CDIP	8	40	502	14	11938	4.32





#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

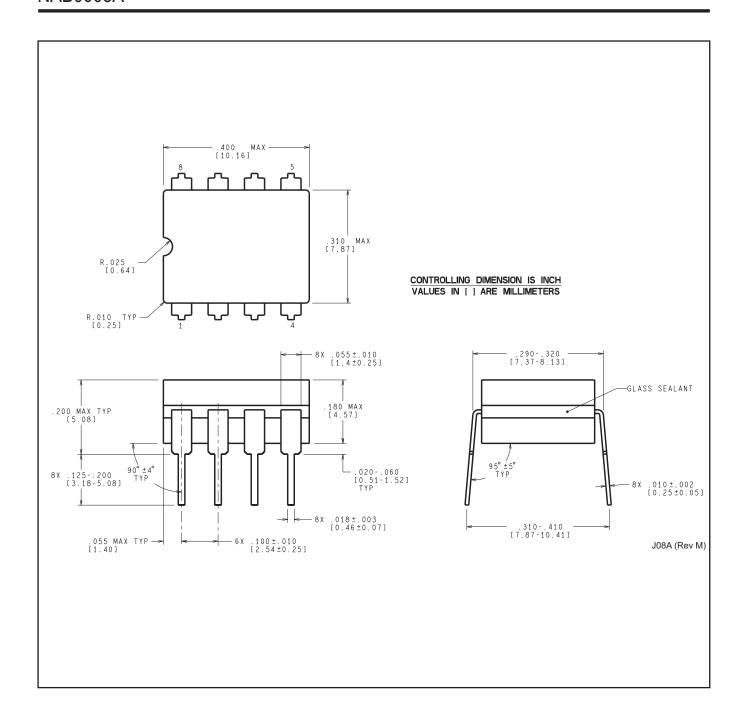




NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.









## NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



# P (R-PDIP-T8)

# PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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